

ABSTRACT

A heating element cooling cover 5 for covering IC devices 44 mounted on a substrate 4, wherein a coolant is circulated to be able to contact the IC devices 44, and a groove 54 (bypass) is provided for an air and the coolant to flow from a gas accumulation part where gas accumulation is liable to be generated inside the heat element cooling cover 5 to a position where the circulating coolant comes downstream of the gas accumulation portion. According to the heat element cooling cover 5, gas accumulation can be effectively removed as a result that the air in the gas accumulation part can pass through the bypass.